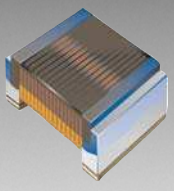


\*RoHS COMPLIANT



**BOURNS®**

**Features**

- 0603 size
- Available in E12 series
- High Q - up to 80 typ.
- High operating temperature of 125 °C
- Small size of only 1.6 mm
- RoHS compliant\*

**Applications**

- Mobile phones
- Cellular phones
- CTV, VCR, HIC, FDD

**CW160808 Series - High Q Chip Inductors**

**Electrical Specifications**

Bourns® Part No.	Inductance		Q	Test Freq. (MHz)		SRF (MHz)	RDC	I rms (mA)
	nH	Tol. %	Min.	L	Q	Min.	Ohms	Max.
CW160808-1N8M	1.8	±20	16	250	250	6000	0.04	700
CW160808-2N2D	2.2	±15	16	250	250	6000	0.08	700
CW160808-3N9J	3.9	±5	16	250	250	6000	0.08	700
CW160808-4N7J	4.7	±5	16	250	250	5800	0.10	700
CW160808-6N8J	6.8	±5	25	250	250	5800	0.11	700
CW160808-8N2J	8.2	±5	30	250	250	5000	0.11	700
CW160808-10NJ	10	±5	30	250	250	4800	0.13	700
CW160808-12NJ	12	±5	30	250	250	4000	0.13	700
CW160808-15NJ	15	±5	30	250	250	4000	0.17	700
CW160808-18NJ	18	±5	30	250	250	3100	0.17	700
CW160808-22NJ	22	±5	35	250	250	3000	0.19	700
CW160808-27NJ	27	±5	35	250	250	2800	0.22	600
CW160808-33NJ	33	±5	35	250	250	2300	0.22	600
CW160808-39NJ	39	±5	35	250	250	2200	0.25	600
CW160808-47NJ	47	±5	35	200	250	2100	0.28	600
CW160808-56NJ	56	±5	35	200	250	1900	0.31	600
CW160808-68NJ	68	±5	35	200	250	1700	0.34	600
CW160808-72NJ	72	±5	34	200	250	1700	0.49	400
CW160808-82NJ	82	±5	34	150	250	1700	0.54	400
CW160808-R10J	100	±5	34	150	250	1400	0.71	400
CW160808-R12J	120	±5	32	150	250	1350	0.79	300
CW160808-R15J	150	±5	28	150	150	1300	0.92	280
CW160808-R18J	180	±5	25	100	100	990	1.25	240
CW160808-R22J	220	±5	25	100	100	990	1.90	200
CW160808-R27J	270	±5	25	100	100	990	2.30	170

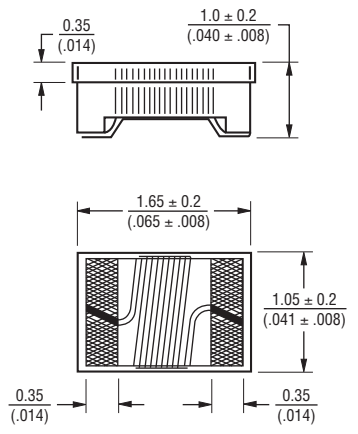
**General Specifications**

Temperature Rise .....20 °C max. at rated current  
 Operating Temperature .....-40 °C to +125 °C  
 Storage Temperature .....-40 °C to +125 °C  
 Reflow Soldering .. 230 °C, 50 sec. max.  
 Resistance to Soldering Heat ..... +260 °C, 10 seconds

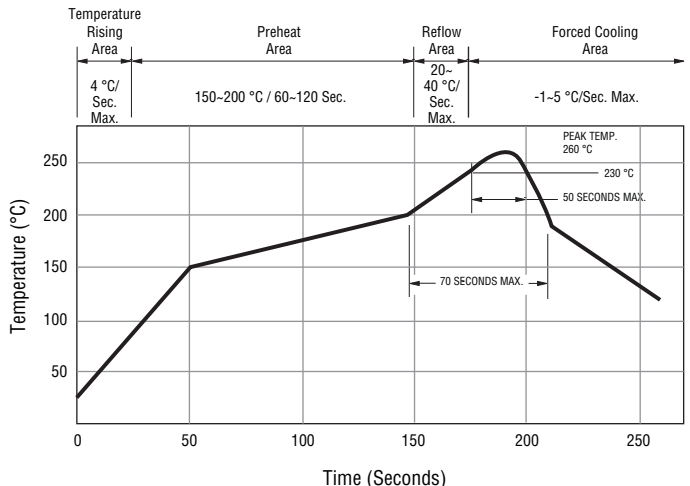
**Materials**

Core Material ..... Alumina (1CC150707-302291)  
 Wire ..... Enameled copper (1W1E180)  
 Terminal ..... Mo/Mn+Ni+Au  
 Encapsulate ..... Epoxy (1EAS-UV300)  
 Packaging ..... 3,000 pcs. per reel

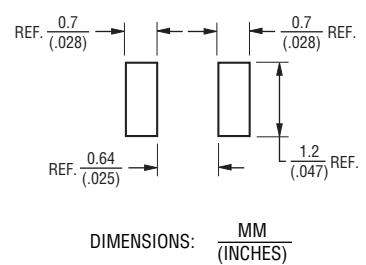
**Product Dimensions**



**Solder Profile**



**Recommended Layout**



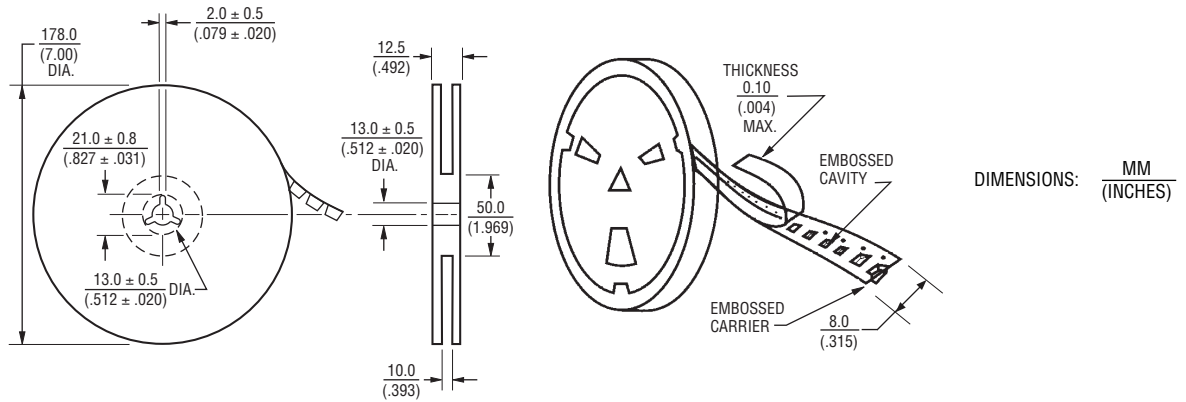
\*RoHS Directive 2002/95/EC Jan. 27, 2003 including annex and RoHS Recast 2011/65/EU June 8, 2011.

Specifications are subject to change without notice. The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time. Users should verify actual device performance in their specific applications.

# CW160808 Series - High Q Chip Inductors

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## Packaging Specifications



REV. 02/13

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